






**Dear Patrons,**

As we look back on August, it is encouraging to see India's electronics and semiconductor ecosystem continue to move forward through meaningful collaborations, growing investments, and a shared commitment to building domestic capabilities.

A key highlight was the **SEMICON India 2026 media briefing**, where IESA joined the Ministry of Electronics and Information Technology (MeitY), the India Semiconductor Mission (ISM), and SEMI to discuss progress under Semicon 1.0 and the expanded vision of Semicon 2.0. Discussions highlighted opportunities across chip design, manufacturing, advanced packaging, research and development, and talent development.

Domestic manufacturing also gained momentum with the fifth tranche of approvals under the **Electronics Component Manufacturing Scheme (ECMS)**, comprising 31 approvals and ₹7,877 crore in committed investments. IESA congratulates its member companies **Centum Electronics Ltd., Accurate Gauging & Instruments Pvt. Ltd., VVDN Technologies, Acutaas Chemicals Limited, and Syrma SGS Technology Limited** on securing approvals.

As the industry expands, developing skilled talent becomes increasingly essential. **Mr. Sundeep Gupta, Executive Committee Member, IESA**, moderated discussions on semiconductor skills at the ET Electronics World Design & Verification Summit 2026 in Bengaluru, highlighting the need for deeper technical expertise and stronger industry–academia collaboration. On 24 August, **Mr. Ashok Chandak, Mr. Dharmendra Singh Yadav, and Mr. Viswanathan K.G**, participated in discussions with NIELIT and SEMI University on integrating their portals for semiconductor courses.

Complementing these efforts, IESA also successfully concluded a Workforce Development Webinar on 25 August, featuring **Mr. Pradeep CR, Senior Director – Applications Engineering, Synopsys Inc.**, who explored the System-on-Chip journey from classroom concepts to real-world applications.

These developments reinforce the importance of a connected ecosystem built on collaboration, innovation, investment, and skills. IESA remains committed to working alongside its members and partners to strengthen India's semiconductor capabilities and advance its position in the global electronics value chain.



Yours Sincerely
**Ashok Chandak**
*President, IESA*



Yours Sincerely
**Navin Bishnoi**
*Chairman, IESA*

# IESA Media & PR Dashboard: August Highlights

### Overall Media Reach (Metric Coverage)

| Total Media Stories | 114 |
|---|---|
| Print | 73 |
| Online | 37 |
| Electronic & Radio | 04 |

### Tier -1/ TV Media Visibility

| Platform | Engagement |
|---|---|
| CNBC TV18 | Exclusive interviews on the government's mobile phone manufacturing scheme |
| ET Edge | India's semiconductor ambitions, investment and manufacturing growth |
| Business Today | Exclusive interviews on Deep Tech's Defining Moment |
| Zee Business | Tax relief for foreign investors |

### Policy & Industry Narrative

| Topic | Platform |
|---|---|
| 1.2 lakh crore Semicon 2.0 annoucement | ET Telecom |
| Discussions on Chennai's growing industrial electronics ecosystem | The Times of India |
| PM lays foundation for ASIP semiconductor plant in Andhra Pradesh | Times of India, Times Tech, The Machinemaker, ET Electronics, IANS Live, The Freedom Press, Bizz Buzz, The Hans India, and DQ India |
| India's growing semiconductor demand | Business Standard |
| Mobile Phone Manufacturing Scheme | CNBC TV18, BusinessWorld, ET Electronics, BusinessLine, IANS and Cellit |

### Regional Media Impact

| Focus Area | Coverage |
|---|---|
| Total overhaul of quality controls needed for doing business: Experts | Financial Express |
| Semiconductor race heats up as conglomerates bet ₹4,000 crore | Mint |
| Creating Creating global IPs global IPs | Financial Express |
| Govt raises semiconductor demand Forecasts 50% to $150 bn by 2030 | Business Standard |
| Red Fort to Silicon Reality: India's Semiconductor Era is on fast Track | Orissa Times, Odisha Khabar, Samaya, Samaja, Biswabani, Odisha Bhaskar, Kalinga Mail, Swantantra Barta, Pragativadi, Manthan, Utkal Samaja, Free Press Gujarat, Sandesh, Gujarat Samachar |

### Social Media Growth

| Platform | Performance |
|---|---|
| LinkedIn | 846 New Followers, 51075 Impressions |
| Twitter/ X Engagement | 787 Impressions, 35+ Engagements |

## Key Takeaways

- IESA's media engagement significantly strengthened policy visibility, industry credibility, collaboration, and national and regional reach, reinforcing IESA and industry partners as a trusted voice in India's ESDM and semiconductor ecosystem.

View PR Coverage Summary



## IESA Joins SEMICON India 2026 Media Briefing

The India Electronics and Semiconductor Association (IESA), alongside MeitY, the India Semiconductor Mission (ISM), and SEMI, participated in the SEMICON India 2026 media briefing in New Delhi. Key speakers included Shri S. Krishnan, Shri Amitesh Kumar Sinha, Mr. Ajit Manocha, and **Mr. Ashok Chandak, President, IESA and SEMI India**. Discussions highlighted progress under Semicon 1.0 and the expanded Semicon 2.0 vision, covering chip design, manufacturing, advanced packaging, R&D, and talent development ahead of the event on 17–19 September 2026.

## New Taxation Bill: A Positive Step for India's ESDM Ecosystem

IESA President **Mr. Ashok Chandak** shared his views on the potential impact of the new Taxation Bill on the electronics and semiconductor sectors during a live discussion on **Zee Business on 4 August 2026**. Highlighting the three Cs—**Credibility, Continuity, and Commitment**—he emphasised their importance in building investor confidence. He noted that the initiative could strengthen India's ESDM ecosystem, attract foreign investment, and benefit the component supply chain, describing it as a positive step towards advancing India's electronics and semiconductor industry.




Watch Full Interview:




## IESA Highlights Semiconductor Talent Priorities at ET Electronics World Summit 2026

**Mr. Sundeep Gupta**, Executive Committee Member, IESA, moderated discussions on semiconductor workforce development at the ET Electronics World Design & Verification Summit 2026 in Bengaluru. The discussions emphasised the need for deeper semiconductor expertise, hands-on chip design experience, AI proficiency, and system-level understanding. Strengthening industry–academia collaboration, practical training, and industry-relevant curricula was identified as essential to developing talent capable of advancing India's semiconductor ecosystem from engineering execution towards greater ownership of intellectual property (IP), chips, and intelligent products.

## Highlights from the NIELIT-SEMI University Portal Integration Meeting



On 24th August, IESA participated in a meeting with NIELIT and SEMI University to discuss integrating their portals for semiconductor courses and learning resources. Representing IESA, **Mr. Ashok Chandak, President; Mr. Dharmendra Singh Yadav, Director – Government Relations and Policy; and Mr. Viswanathan K.G., Director – Workforce Development, joined the discussions. The initiative aims to improve access to industry-relevant semiconductor training, strengthen workforce development**, and support the creation of a skilled talent pool for India's growing semiconductor ecosystem.




## IESA Congratulates Members on ECMS Approvals

IESA congratulates its member companies **Centum Electronics Ltd., Accurate Gauging & Instruments Pvt. Ltd., VVDN Technologies, Acutaas Chemicals Limited, and Syrma SGS Technology Limited** on securing approvals under the fifth tranche of the Electronics Component Manufacturing Scheme (ECMS). With 31 new approvals and ₹7,877 crore in committed investments, the initiative strengthens India's domestic electronics manufacturing ecosystem. The scheme is expected to boost component localisation, strengthen supply chains, generate employment, and advance India's vision of a globally competitive, self-reliant electronics industry.

## IESA Workforce Development Webinar Explores the SoC Journey

IESA hosted a Workforce Development Webinar on **"The Journey of an SoC: C2C (Classroom to Consumer)"** on 25 August 2026. The session featured **Mr. Pradeep CR, Senior Director – Applications Engineering at Synopsys Inc.**, who shared insights into the System-on-Chip (SoC) lifecycle, from concept and design to validation, deployment, and real-world applications. The webinar highlighted the importance of practical industry knowledge in strengthening semiconductor skills and preparing students, aspiring professionals, and engineers for the evolving semiconductor ecosystem.



# StartUp / MSMEs of the Month - September 2026

**Company Name:** Siliciom Technologies Pvt. Ltd.

**Location:** HQ – Benguluru, Presence in Hyderabad, Noida, Pune

**Website:** https://siliciom.com/

**Email ID:** info@siliciom.com / Sanjay_k@siliciom.com

**Overview:**

Siliciom is fastest growing semiconductor services company with wide range of expertise in high speed designs, automotive, 5G, AI , High compute machines.

**Highlights:**

- End-to-End Solutions: From Architecture & RTL through Physical Design, Verification and Post-silicon Validation — one partner for your full chip journey.
- Expert Engineering Team: 120+ engineers specializing in RTL, DV, DFT, physical design and embedded across the latest process nodes.
- Proven First Pass Silicon: Track record across 3nm–28nm nodes with successful tape-outs for automotive, Networking, Data Center & Optical
- Customer First Partnership: Tailored engagement models — Augmentation, Turnkey, or ASIC-as-a-service—aligned to your timeline and budget.
- Time-to-Market Speed: Rapid ramp-up with mature flows, reusable IP environments and parallel execution across design and verification.
- Quality & Reliability: Rigorous sign-off checklists, CDC/Lint/Formal flows and a culture of zero-defect delivery.

**Key Products/ Services/ Highlight:**

- SoC / IP RTL Design: Architecture, Micro-Architecture, RTL coding, Low Power, CDC/Lint flows
- Protocols: PCIe, CXL, UCIe, HBM, DDRx, AMBA
- Pre-Silicon Verification: UVM/SV, Formal, Functional Coverage, Power Aware; IP / Subsystem / SoC-level; First-pass silicon guarantee
- DFT & Physical Design: Synthesis, PNR, STA Sign-off, LEC<PDN, DRC/LVS3nm and above IP Hardening: DDR, PCIe, Ethernet, ARM
- Post-Silicon Validation: Power & Performance validation, Hardware interface characterization; bridging pre/post silicon gaps swiftly
- Software & Embedded: Firmware development, driver integration, Hardware/Software co-verification for complex SoC platforms
- Reference Hardware Design: Board and system-level reference designs supporting customer SoC bring-up and ecosystem

# StartUp / MSMEs of the Month - September 2026

**Company Name:** Tylsemi Solutions Pvt. Ltd.

**Location:** Tylsemi Solutions Pvt Ltd Suite 9, 11th Floor, Gopalan Fortune City, Mahadevapura, Kagadarapura village, KR Puram hobli, Bengaluru East taluk, Bengaluru – 560048

**Website:** https://www.tylsemi.ai/

**Email ID:** amondal@tylsemi.ai

**Overview:**

TYLsemi™ is a chiplet-first silicon company focused on AI infrastructure. TYLsemi™ deliver production-ready chiplets for connectivity, power, and efficiency, enabling teams to build advanced systems without the cost and complexity of designing critical silicon from scratch. Built for rapid real-world deployment, the chiplets integrate directly into multi-die systems, accelerating development and reducing risk. For customers requiring complete solutions, TYLsemi™ extend this platform to full custom silicon, delivering production-ready systems at scale.

**Key Products/ Services/ Highlight:**

TYLsemi™ delivers production-ready chiplets for the core functions of AI infrastructure, plus custom silicon development for complete system solutions.